

www.ti.com SWRS130 – OCTOBER 2012

Bluetooth® Module that is Bluetooth Low Energy - Smart Ready from LS Research

FEATURES

- Bluetooth 2.1+EDR and BLE 4.0
- Power Class 1.5
- Miniature Footprint: 7 mm x 7 mm
- Low Height Profile: 1.5 mm
- Certified with off Module Chip and Dipole Antennas
- Integrated Band-Pass Filter
- Worldwide Acceptance: FCC (USA), IC (Canada), and CE (Europe)
- Compact Design Based on Texas Instruments CC2564 Transceiver
- HCI UART Host Data Path Interface
- Bluetooth Advanced Audio Interfaces
- Low Power Operation Mode
- RoHS Compliant
- Streamlined Development with LSR Design Services

APPLICATIONS

- Medical
 - Heart Rate Monitor, Blood Pressure Sensor, Blood Glucose Meter
- Thermometer
- Flood Alarm
- Heating Control
- Automatic Key Control
- Industrial Sensors
- Toys
- Entertainment Devices
- Mobile Accessoriesn
- All Bluetooth Wireless Applications)

DESCRIPTION

TiWi-uB2 is a low-cost and low power consumption module which has all of the *Bluetooth* functionalities. The highly integrated module makes the use of *Bluetooth* headsets and other applications possible. The TiWi-uB2 module fully supports the dual mode *Bluetooth* and BLE operation, and the output power can support class 1.5. The SIP module provides UART interface / audio PCM interface for *Bluetooth*.

The TiWi-uB2 *Bluetooth* module is a high performance 2.4 GHz *Bluetooth* 2.1+EDR and *Bluetooth* Low Energy - Smart Ready radio in a cost effective, pre-certified footprint. This module provides a *Bluetooth* platform through the HCI transport layer.

More information on the product can be found on LSR's website:

- Product Overview:http://www.lsr.com/wireless-products/tiwi-ub2
- Data sheet: http://www.lsr.com/downloads/products/330-0100.pdf

More information on TI's wireless platform solutions for *Bluetooth* can be found on TI's Wireless Connectivity Wiki (www.ti.com/connectivitywiki).

M

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Bluetooth is a registered trademark of Bluetooth SIG, Inc. All other trademarks are the property of their respective owners.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

Products Applications

Audio Automotive and Transportation www.ti.com/automotive www.ti.com/audio **Amplifiers** amplifier.ti.com Communications and Telecom www.ti.com/communications **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers DI P® Products Consumer Electronics www.dlp.com www.ti.com/consumer-apps

DSP dsp.ti.com **Energy and Lighting** www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface Medical www.ti.com/medical interface.ti.com Logic logic.ti.com Security www.ti.com/security

Power Mgmt <u>power.ti.com</u> Space, Avionics and Defense <u>www.ti.com/space-avionics-defense</u>

Microcontrollers microcontroller.ti.com Video and Imaging www.ti.com/video

RFID www.ti-rfid.com

OMAP Applications Processors www.ti.com/omap TI E2E Community e2e.ti.com

Wireless Connectivity <u>www.ti.com/wirelessconnectivity</u>